



Capabilities

Specifications:	Standard	High-Tech			Next Step		
Base Material Used	FR4 – FR4 HiTg°	BT Epoxy - Polyimide - Teflon - INVAR - Halogen Free - Hi Frequency			BT Epoxy - Polyimide - Teflon - INVAR - Halogen Free - Hi Frequency		
PCB Type	Rigid	Rigid	Rigid (hybrid)	Rigid/Flex	Rigid	Rigid (hybrid)	Rigid/Flex (Teflon+Kapton)
Maximum Number of Layers	16	36	32	24	40	40	32
Maximum Board Dimension	570 x 449	640x570 mm					
Maximum Board Thickness	3,2 mm	6.5 mm					
Minimum core Thickness	0,1 mm	0,05 mm - 0,025 (Flex)					
Base Copper Thickness	18 - 35 - 70 μ	9-12-18-35-70-105-140-210-305 μ					
Aspect Ratio	8:1	24:1			30:1		
Minimum Diameter Hole (Mechanical)	0.2 mm	0,15 mm			0.1 mm		
Minimum Diameter Hole (Laser)	100 μ	75 μ			60 μ		
Nickel Thickness on the Connector	> 4 μ	> 4 μ					
Gold Thickness on the Connector	> 0,8 μ	> 0,8 μ					
Holes Position Tolerance	\pm 0,1 mm (from the board edge)	\pm 0,07 mm on PCB with diagonal < 300 mm (from the board edge)					
Minimum Trace	100 μ	75 μ			50 μ		
Minimum Space	100 μ	75 μ			50 μ		
Plated Hole Tolerance	-0,05 \div + 0,1 mm	-0,05 \div + 0,05 mm					
Unplated Hole Tolerance	0 \div + 0,1 mm	0 \div + 0,1 mm					
Conformity Certificate	On demand	On demand					
Test Certificate	On all delivery	On all delivery					
Controlled Impedance Certification	On demand	On demand					
Production Date (week and year)	On solder mask On copper (on demand)	On solder mask On copper (on demand)					
Certification	Vision 2000 - ISO TS 16949-2002 UL Certified: 94V-0 up to 130°	Vision 2000 - CNES - AS9100B EN9100:2003/S1 - JISQ9100:2004 UL Certified: 94V-0 up to 130°			ISO 14000		
Routing Tolerance	\pm 0,2 mm	\pm 0,15 mm					
Surface Finishes	H.A.S.L. - Lead Free H.A.S.L. Electroless Gold Electroless Tin - OSP	Electrolytic Ni - Electrolytic NiAu					
Solder Mask Types	Photographic	Photographic					
Legend	White	Different Colours					
Electrical Test (short and open)	100%	100%					